

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		PTVS45VP1UTP-Q Part Description						
								Nexperia DHAM
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
			TEST					
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	524	22940	0		
ı		MIL-STD-750-1						
	HTRB	M1038 Method A						
	High Temperature Reverse Bias	Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	DIdS	reverse voltage	1000 hours	205	9400	0		
	TC	JECD22 A104						
# 4.4	TC Temperature Cycling	JESD22-A104 -65 °C to Timax, not to exceed 150°C	1000	156	7000	0		
# A4	remperature cycling	os e to rimax, not to exceed 150 e	1000 cycles	156	7080	0		
	UHAST	JESD22-A118						
# A3 <b>or</b>	Unbiased HAST	Tamb = 130 °C, RH = 85 %	— 96 hours	156	7080	0		
		JESD22-A102						
	AC	Tamb = 121 °C, RH = 100 %						
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)						
		<u> </u>						
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	156	7080	0		
		MIL-STD-750 Method 1037						
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =						
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.		
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	56	1700	0		
	SD							
# C10	Solderability	J-STD-002		56	1700	0		

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	9400	0	0,45	2,21E+09

<sup>© 2024</sup> Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com